

## Surface Mount Technology Association Press Release

**For more info contact:**  
**Patti Hvidhyld**  
**T 952-920-7682**  
**patti@smta.org**



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### **IWLPC Best Papers Announced**

**Minneapolis, MN** – SMTA and *Chip Scale Review magazine*, co-organizers of the International Wafer-Level Packaging Conference (IWLPC), announced the Best of Conference papers from the event held November 5-7, 2013 in San Jose. Winners were selected from each of the three tracks covering Wafer Level Packaging, 3-D (Stacked) Packaging, and MEMS Packaging, as well as an overall Best of Conference winner.

The Best of Conference and winner of the 3D track was Jessica Fredlund, Silex Microsystems AB, for her paper, "Recent Results Using Met-Via TSV Interposer Technology as TMV Element in Wafer Level Through Mold Via Packaging of CMOS Biosensors." Co-authors include Toby Ebefors, Silex Microsystems AB; Erik Jung and Tanja Braun, Ph.D., Fraunhofer IZM.

Sumant Sood of SUSS MicroTec won the Best of MEMS Track for his paper, "Advanced Metal-Eutectic Bonding for High Volume MEMS WLP." Co-authors include Robert Hergert, SUSS MicroTec and Oliver Treichel, SUSS MicroTec Lithography.

William "Boyd" Rogers of DECA Technologies won the Best of Wafer-Level Packaging Track for his paper, "Implementation of a Fully Molded Fan-Out Packaging Technology." Co-authors include Chris Scanlan and Tim Olson, also from DECA Technologies.

All thirty-nine of the conference papers can be found on the conference proceedings available in the [online SMTA BookStore](#).

The IWLPC Technical Committee is currently soliciting abstracts for next year's program. Interested parties should submit 200-300 word abstracts online at [http://www.iwlpc.com/call\\_for\\_papers.cfm](http://www.iwlpc.com/call_for_papers.cfm) by April 18, 2014. Note that technical papers are required and are due August 22, 2014.

IWLPC will return to the DoubleTree Hotel in San Jose, California on November 11-13, 2014. Visit <http://www.iwlpc.com/> for more information.

*The SMTA membership is an international network of professionals who build skills, share practical experience and develop solutions in electronic assembly technologies, including microsystems, emerging technologies, and related business operations.*

*Chip Scale Review, now in its 17th year, is the leading international magazine serving the semiconductor, IC and electronic device packaging market.*

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